

**TRADEMARK ASSIGNMENT**

Electronic Version v1.1  
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNS THE ENTIRE INTEREST AND THE GOODWILL
EFFECTIVE DATE:	11/30/2005

**CONVEYING PARTY DATA**

Name	Formerly	Execution Date	Entity Type
TERADYNE, INC.		11/30/2005	CORPORATION: MASSACHUSETTS

**RECEIVING PARTY DATA**

Name:	AMPHENOL CORPORATION
Street Address:	358 Hall Avenue
City:	Wallingford
State/Country:	CONNECTICUT
Postal Code:	06492
Entity Type:	CORPORATION: DELAWARE

**PROPERTY NUMBERS Total: 12**

Property Type	Number	Word Mark
Serial Number:	78682550	CROSSBOW
Serial Number:	78418881	VENTURA
Serial Number:	78514820	APTERA
Serial Number:	78297381	DIFFERENTIAL CLEARANCE TECHNOLOGY
Serial Number:	75383873	VHDM
Serial Number:	78470448	DESIGNLINK
Registration Number:	2669292	NEXLEV
Registration Number:	2779372	GBX
Registration Number:	2426683	BRINGING BANDWIDTH TO THE GLOBAL NETWORK
Registration Number:	1894556	HDM PLUS
Registration Number:	1886552	HDM
Registration Number:	1494014	HIGH DENSITY PLUS (HD+)

CH \$315.00 78682550

CORRESPONDENCE DATA

Fax Number: (202)772-5858  
*Correspondence will be sent via US Mail when the fax attempt is unsuccessful.*  
Phone: 202-944-3000  
Email: weissman@blankrome.com  
Correspondent Name: Blank Rome LLP  
Address Line 1: 600 New Hampshire Avenue, N.W.  
Address Line 4: Washington, DISTRICT OF COLUMBIA 20037

ATTORNEY DOCKET NUMBER:	124315.00100
NAME OF SUBMITTER:	Peter Weissman
Signature:	/psw/
Date:	02/28/2006

Total Attachments: 32  
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**INTELLECTUAL PROPERTY ASSIGNMENT AGREEMENT  
AND LICENSE AGREEMENT**

This Intellectual Property Assignment Agreement and License Agreement (this "Agreement") is made this 30<sup>th</sup> day of November, 2005 (the "Effective Date"), by and between Teradyne, Inc., a Massachusetts corporation ("Assignor") and Amphenol Corporation, a Delaware corporation ("Buyer").

RECITALS

WHEREAS, Buyer and Teradyne, Inc. have entered into an Asset and Stock Purchase Agreement dated October 10, 2005 (the "Purchase Agreement"), pursuant to which Buyer shall purchase certain assets related to the Business (capitalized terms used herein and not otherwise defined shall have the respective meanings set forth in the Purchase Agreement);

WHEREAS, pursuant to the Purchase Agreement, Assignor desires to transfer and assign to Buyer, and Buyer desires to accept the transfer and assignment of all of Assignors' right, title and interest in and to the Purchased Intellectual Property including that Intellectual Property listed on Schedule A attached hereto, and to license to Buyer certain trademark rights for the use of those marks listed on Schedule C subject to certain conditions as identified herein;

WHEREAS, Buyer is willing to grant a limited license to Assignor with respect to certain Intellectual Property set forth on Schedule B transferred pursuant to the Purchase Agreement for internal use and for use in connection with its Products;

NOW, THEREFORE, for valuable consideration, the sufficiency of which is hereby mutually acknowledged, the parties agree as follows:

1. THE ASSIGNMENT OF INTELLECTUAL PROPERTY RIGHTS BY ASSIGNOR TO BUYER

Pursuant and subject to the Purchase Agreement, Assignor does hereby transfer, assign, convey and deliver to Buyer, and its Affiliates, successors and assigns, and Buyer hereby accepts the transfer and assignment of all of Assignor's right, title and interest in, to and under the Purchased Intellectual Property including the Intellectual Property listed on Schedule A attached hereto, and including, to the extent included therein: (i) all of the goodwill associated therewith; (ii) all rights to recover for infringement associated therewith whether arising prior to or subsequent to the date of this Assignment; (iii) all inventions disclosed therein and all divisionals, continuations, continuations-in-part, substitutes, renewals, reissues, reexaminations or other applications which have been or may be filed in the United States or any foreign country on any of said inventions, (iv) all patents which may be granted therefore throughout the world, including the right to file applications and obtain patent grants, utility models, industrial models and designs for any of said inventions in its own name throughout the world, and (v) all rights of priority, all rights to publish cautionary notices reserving ownership of said inventions, and all rights to register said inventions in appropriate registries.

To the extent that this Agreement is not acceptable for purposes of recording in a necessary office to indicate transfer to Buyer of any of the Purchased Intellectual Property, including the Intellectual Property listed on Schedule A, then in addition to this Agreement and without limiting its obligations under Section 4, for a period of one hundred eighty (180) days after the Closing or such other time period reasonably necessitated or required by local jurisdiction in question to achieve the transfer, Assignor and its Affiliates agree to execute individual assignments of all of the Purchased Intellectual Property including the Intellectual Property listed on Schedule A attached hereto, with respect to those individual countries where this Agreement is not acceptable for recording, which assignments shall be executed, and, where required, notarized and/or legalized apostille, on behalf of Assignor. The form of assignment or transfer shall be that used customarily in the jurisdiction in question to achieve the transfer on the terms set forth above. Buyer and Assignor shall each be responsible for fifty percent (50%) of the costs of filing or recording the assignments of all of the Purchased Intellectual Property in a necessary office to indicate transfer to Buyer.

## 2. THE LICENSE OF INTELLECTUAL PROPERTY RIGHTS BY BUYER TO ASSIGNOR

Buyer hereby grants to Assignor and its Affiliates, and their permitted successors and assigns, a limited, non-exclusive, perpetual, irrevocable, worldwide, royalty-free, non-sublicensable license under the Intellectual Property Rights listed in Schedule B, to design, have designed, use, have used, manufacture, have manufactured, market, sell, offer to sell, distribute (directly and indirectly), import and export:

- (i) Assignor's and its Affiliates', current and future end products and/or subassemblies which contain a printed circuit board, backpanel, backplane, or equivalent structure;
- (ii) printed circuit boards, backpanels, backplanes, or equivalent structures, for use only in Assignor's and its Affiliates' current and future products, sold or provided as spare, repair or replacement parts;
- (iii) products used internally by Assignor and its Affiliates, or used internally by subcontractors, to manufacture products for Assignor and its Affiliates; and
- (iv) in the case of DesignLink software and its intellectual property identified in Schedule B, to be used internally by Assignor and its Affiliates or externally by their customers,

which, except for the limited license granted herein, would infringe a right conferred by the Intellectual Property Rights identified on Schedule B.

The rights granted hereunder are not intended to nor shall be they be construed to minimize or limit the noncompetition restrictions contained in Section 5.05(a) of the Purchase Agreement.

Assignor agrees that Buyer has no obligation to maintain or continue the prosecution of any provisional or pending patent applications listed in Schedule B; provided that, at least ninety (90) days before allowing any such provisional or pending applications to lapse, Buyer will provide notice to Assignor, whereupon Assignor will have the option to maintain or continue prosecution of such provisional or pending applications at Assignor's expense. In such an event,

Assignor will assume all ownership rights in the provisional or pending applications and Buyer agrees to assign such ownership rights to Assignor; provided that, in such event Assignor shall grant Buyer a license under such Patent substantially similar to the license granted to Assignor in this Section 2.

Assignor acknowledges that a breach of the license granted by Buyer in this Section 2 may cause the Buyer irreparable damage, for which the award of damages alone may not be adequate compensation and the Buyer is therefore entitled to seek injunctive relief to enjoin the Assignor from violation of those provisions. Such injunctive relief remedy shall be cumulative and not exclusive and the Buyer is entitled to seek any other relief available to it at law or in equity.

### 3. THE LICENSE OF CERTAIN TRADEMARK RIGHTS BY ASSIGNOR TO BUYER

For a term of not more than two (2) years from the Effective Date, Assignor hereby grants to Buyer, and its Affiliates, successors and assigns, a non-exclusive, worldwide, royalty-free, non-transferable right and license to the rights Assignor has to the mark set forth on Schedule C (hereinafter "Licensed Mark") only on products formerly offered by Assignor's TCS division and only in conjunction with the word "Amphenol" (for example "an Amphenol TCS product" or "an Amphenol product formerly manufactured by TCS"). Buyer may continue to use Assignor's existing inventory of stationary, business cards, marketing literature, preprinted documents, and similar materials that are branded only with the Licensed Mark but not any other trademark of Assignor (for example, excluding any materials branded with the word "Teradyne") until such existing supply is exhausted. This license does not extend to the use by Buyer of the Licensed Mark on a stand-alone basis.

Buyer agrees that its use of the Licensed Mark will be in accordance with applicable law and Assignor's reasonable policies regarding advertising and trademark usage as published from time to time by Assignor. Buyer agrees to use the Licensed Mark in a manner reasonably consistent with the established standards of quality and goodwill associated with the Licensed Mark prior to the Effective Date. If, in Assignor's sole discretion, Assignor reasonably determines that Buyer's use of the Licensed Mark harms, tarnishes, dilutes or damages the goodwill associated with the Licensed Mark, Assignor shall notify Buyer in writing and Buyer shall correct any such use within ten (10) business days of receipt of such notice or Assignor may unilaterally terminate this license in the Licensed Mark.

In order to verify compliance with this Section 3 of this Agreement, Assignor may from time to time require that Buyer provide samples of Buyer's marketing materials that bear the Licensed Mark.

### 4. FURTHER ASSURANCES

Assignor and Buyer hereby further agree, each for itself and its successors, assigns, and legal representatives, to execute upon request any other lawful documents and likewise to perform any other lawful acts that are necessary to secure fully the aforesaid rights, titles, and interests in and to said Purchased Intellectual Property.

## 5. EXECUTION OF COUNTERPARTS

This Assignment may be executed in one or more counterparts, each of which will be deemed to be an original copy of this Assignment and all of which, when taken together, will be deemed to constitute one and the same agreement. The exchange of copies of this Assignment and of signature pages by facsimile transmission shall constitute effective execution and delivery of this Assignment as to the parties and may be used in lieu of the original Assignment for all purposes. Signatures of the parties transmitted by facsimile shall be deemed to be their original signatures for all purposes.

## 6. ENTIRE AGREEMENT; AMENDMENT

Together with the Purchase Agreement and the Ancillary Agreements (as defined therein), this document contains the entire agreement relating to the subject matter contained herein and supersedes all prior or contemporaneous agreements, written or oral, between the parties. This Agreement may not be modified except by written document signed by an authorized representative of each party.

## 7. PRECEDENCE

This Agreement is executed and delivered pursuant to, and is subject to, the Purchase Agreement. In the event of any conflict between the terms of the Purchase Agreement and the terms of this Agreement, the terms of the Purchase Agreement shall prevail.

## 8. SEVERABILITY

Any provision of this Agreement which is invalid, illegal or unenforceable in any jurisdiction shall, as to that jurisdiction, be ineffective to the extent of such invalidity, illegality or unenforceability, without affecting in any way the remaining provisions hereof in such jurisdiction or rendering that or any other provision of this Agreement invalid, illegal or unenforceable in any other jurisdiction.

## 9. GOVERNING LAW

This Agreement shall be construed in accordance with and governed by the laws of the State of New York, without regard to the conflicts of law rules of such state.

## 10. ASSIGNMENT

This Agreement and the rights and licenses hereunder granted are not assignable by Assignor without the written consent of Buyer except, with reasonable notice to Buyer: (i) to an Affiliate of Assignor; (ii) in connection with an assignment of all or substantially all of the assets of Assignor or a business division of Assignor.

**[REMAINDER OF PAGE LEFT INTENTIONALLY BLANK]**

IN WITNESS WHEREOF, the parties have caused this ASSIGNMENT to be duly executed and delivered as of November 30, 2005.

**ASSIGNOR:**

**TERADYNE, INC.**

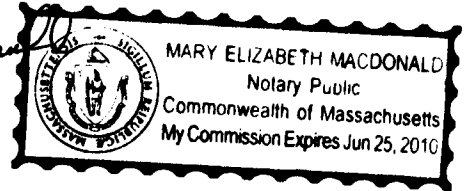
State of Massachusetts ss.:  
County of Suffolk

By: [Signature]  
Name:  
Title:

On this 30 day of NOV., 2005, before me, personally appeared Gregory R. Beecher, of VP&CFO, of Teradyne, Inc. personally known to me (or proved to me on the basis of satisfactory evidence consisting of \_\_\_\_\_) to be the person whose name is subscribed to the within instrument and acknowledged to me that he executed the same in his authorized capacity and that by his signature on the instrument the person, or the entity upon behalf of which the person acted, executed the instrument.

Witness my hand and official seal.

Mary Elizabeth Macdonald  
Notary Public 6/25/2010



**BUYER:**

**AMPHENOL CORPORATION**

State of \_\_\_\_\_ ss.:  
County of \_\_\_\_\_

By: \_\_\_\_\_  
Name:  
Title:

On this \_\_\_\_\_ day of \_\_\_\_\_, 2005, before me, personally appeared \_\_\_\_\_, of \_\_\_\_\_, personally known to me (or proved to me on the basis of satisfactory evidence consisting of \_\_\_\_\_) to be the person whose name is subscribed to the within instrument and acknowledged to me that he executed the same in his authorized capacity and that by his signature on the instrument the person, or the entity upon behalf of which the person acted, executed the instrument.

Witness my hand and official seal.

\_\_\_\_\_  
Notary Public

**SIGNATURE PAGE TO INTELLECTUAL PROPERTY ASSIGNMENT**

IN WITNESS WHEREOF, the parties have caused this ASSIGNMENT to be duly executed and delivered as of November 30, 2005.

**ASSIGNOR:**

TERADYNE, INC.

(State of \_\_\_\_\_) ss.:  
(County of \_\_\_\_\_)

By: \_\_\_\_\_  
Name:  
Title:

On this \_\_\_\_\_ day of \_\_\_\_\_, 2005, before me, personally appeared \_\_\_\_\_, of \_\_\_\_\_, personally known to me (or proved to me on the basis of satisfactory evidence consisting of \_\_\_\_\_) to be the person whose name is subscribed to the within instrument and acknowledged to me that he executed the same in his authorized capacity and that by his signature on the instrument the person, or the entity upon behalf of which the person acted, executed the instrument.

Witness my hand and official seal.

\_\_\_\_\_  
Notary Public

**BUYER:**

AMPHENOL CORPORATION

(State of Connecticut) ss.: **Wallingford**  
(County of New Haven)

By: Timothy F. Cohane  
Name: **Timothy F. Cohane**  
Title: **Executive V.P.**

On this 30 day of November, 2005, before me, personally appeared TIMOTHY F. COHANE, of AMPHENOL CORPORATION personally known to me (or proved to me on the basis of satisfactory evidence consisting of N.A.) to be the person whose name is subscribed to the within instrument and acknowledged to me that he executed the same in his authorized capacity and that by his signature on the instrument the person, or the entity upon behalf of which the person acted, executed the instrument.

Witness my hand and official seal.

Mary Ann Aftosmes  
Notary Public MARY ANN AFTOSMES  
My Commission Expires: September 30, 2008

[SIGNATURE PAGE TO INTELLECTUAL PROPERTY ASSIGNMENT]



## SCHEDULE A

### Intellectual Property Assigned by Assignor to Buyer

**Patents:**

Case #	Country	Patent #	Issue Date	Filing Date	Status
0007	CA	1274887	02-Oct-1990	07-Jan-1987	Granted
					<b>Title:</b> DAUGHTER BOARD BACKPLANE ASSEMBLY
0007	JP	1587364		10-Jan-1987	Granted
					<b>Title:</b> DAUGHTER BOARD BACKPLANE ASSEMBLY
0007	US	4686607	11-Aug-1987	08-Jan-1986	Granted
					<b>Title:</b> DAUGHTER BOARD BACKPLANE ASSEMBLY
0008	CA	1312146	29-Dec-1992	22-Sep-1989	Granted
					<b>Title:</b> PRINTED CIRCUIT BOARDS WITH IMPROVED ELECTRICAL CURRENT CONTROL
0008	DE	4002025	11-Sep-1997	31-Jan-1990	Granted
					<b>Title:</b> PRINTED CIRCUIT BOARDS WITH IMPROVED ELECTRICAL CURRENT CONTROL
0008	FR	2642255		26-Jan-1990	Granted
					<b>Title:</b> PRINTED CIRCUIT BOARDS WITH IMPROVED ELECTRICAL CURRENT CONTROL
0008	GB	2229042		26-Jan-1990	Granted
					<b>Title:</b> PRINTED CIRCUIT BOARDS WITH IMPROVED ELECTRICAL CURRENT CONTROL
0008	US	5038252	06-Aug-1991	26-Jan-1989	Granted
					<b>Title:</b> PRINTED CIRCUIT BOARDS WITH IMPROVED ELECTRICAL CURRENT CONTROL
0009	CA	1236187	03-May-1988	18-Nov-1986	Granted
					<b>Title:</b> BACKPLANE-DAUGHTER BOARD CONNECTOR
0009	US	4659155	21-Apr-1987	19-Nov-1985	Granted
					<b>Title:</b> BACKPLANE-DAUGHTER BOARD CONNECTOR
0010	US	4871321	03-Oct-1989	22-Mar-1988	Granted
					<b>Title:</b> ELECTRICAL CONNECTOR
0012	DE	4411187	05-Oct-2000	30-Mar-1994	Granted
					<b>Title:</b> POWER CONNECTOR
0012	FR	2703518	20-Sep-1996	31-Mar-1994	Granted
					<b>Title:</b> POWER CONNECTOR
0012	JP	2706619	09-Oct-1997	31-Mar-1994	Granted
					<b>Title:</b> POWER CONNECTOR
0012	US	5360349	01-Nov-1994	31-Mar-1993	Granted
					<b>Title:</b> POWER CONNECTOR

Case #	Country	Patent #	Issue Date	Filing Date	Status
0016	US	4909743	20-Mar-1990	14-Oct-1988	Granted
					<b>Title: ELECTRICAL CONNECTOR</b>
0017	CA	1245733	29-Nov-1988	16-Aug-1985	Granted
					<b>Title: BACKPLANE CONNECTOR</b>
0057	CA	2119500	24-Nov-1998	21-Mar-1994	Granted
					<b>Title: SHIELDED ELECTRICAL CONNECTOR</b>
0057	DE	4410047D	28-Sep-2000	23-Mar-1994	Granted
					<b>Title: SHIELDED ELECTRICAL CONNECTOR</b>
0057	FR	2706223	04-Jul-1997	29-Mar-1994	Granted
					<b>Title: SHIELDED ELECTRICAL CONNECTOR</b>
0057	FR	2707045	23-Oct-1998	01-Jul-1994	Granted
					<b>Title: SHIELDED ELECTRICAL CONNECTOR</b>
0057	GB	2276989	29-Jan-1997	25-Mar-1994	Granted
					<b>Title: SHIELDED ELECTRICAL CONNECTOR</b>
0057	JP	2739922	23-Jan-1998	04-Apr-1994	Granted
					<b>Title: SHIELDED ELECTRICAL CONNECTOR</b>
0057	US	5403206	04-Apr-1995	02-Apr-1993	Granted
					<b>Title: SHIELDED ELECTRICAL CONNECTOR</b>
0057	US	5605476	25-Feb-1997	07-Jun-1995	Granted
					<b>Title: SHIELDED ELECTRICAL CONNECTOR</b>
0057	US	5484310	16-Jan-1996	06-Mar-1995	Granted
					<b>Title: SHIELDED ELECTRICAL CONNECTOR</b>
0057	US	5607326	04-Mar-1997	17-Jun-1996	Granted
					<b>Title: SHIELDED ELECTRICAL CONNECTOR</b>
1009	US	5704793	06-Jan-1998	17-Apr-1995	Granted
					<b>Title: HIGH SPEED, HIGH DENSITY CONNECTOR FOR ELECTRONIC SIGNALS</b>
1009	US	5820397	13-Oct-1998	21-May-1997	Granted
					<b>Title: HIGH SPEED, HIGH DENSITY CONNECTOR FOR ELECTRONIC SIGNALS</b>
1011	DE	69510956.1	21-Jul-1999	04-Dec-1995	Granted
					<b>Title: PRINTED CIRCUIT BOARD CONNECTORS</b>
1011	EP	00803136	21-Jul-1999	04-Dec-1995	Granted
					<b>Title: PRINTED CIRCUIT BOARD CONNECTORS</b>
1011	FR	00803136	21-Jul-1999	04-Dec-1995	Granted
					<b>Title: PRINTED CIRCUIT BOARD CONNECTORS</b>
1011	GB	00803136	21-Jul-1999	04-Dec-1995	Granted
					<b>Title: PRINTED CIRCUIT BOARD CONNECTORS</b>
1011	US	5595490	21-Jan-1997	13-Jan-1995	Granted
					<b>Title: PRINTED CIRCUIT BOARD CONNECTORS</b>
1016	DE	0829117	05-Jul-2000	04-Mar-1996	Granted
					<b>Title: SURFACE MOUNTED ELECTRICAL CONNECTOR</b>
1016	GB	0829117	05-Jul-2000	04-Mar-1996	Granted
					<b>Title: SURFACE MOUNTED ELECTRICAL CONNECTOR</b>
1016	US	6152742	28-Nov-2000	31-May-1995	Granted
					<b>Title: SURFACE MOUNTED ELECTRICAL CONNECTOR</b>

Case #	Country	Patent #	Issue Date	Filing Date	Status
1016	US	6042386	28-Mar-2000	18-Sep-1998	Granted
<b>Title:</b> SURFACE MOUNTED ELECTRICAL CONNECTOR					
1041	US	5672064	30-Sep-1997	21-Dec-1995	Granted
<b>Title:</b> STIFFENER FOR ELECTRICAL CONNECTOR					
1054	US	5690504	25-Nov-1997	13-May-1996	Granted
<b>Title:</b> PLASTIC GUIDE PIN WITH STEEL CORE					
1056	DE	69722392.2	28-May-2003	06-Feb-1997	Granted
<b>Title:</b> Electrical Connector Assembled From Wafers					
1056	EP	0890201	28-May-2003	06-Feb-1997	Granted
<b>Title:</b> Electrical Connector Assembled From Wafers					
1056	FR	0890201	28-May-2003	06-Feb-1997	Granted
<b>Title:</b> Electrical Connector Assembled From Wafers					
1056	GB	0890201	28-May-2003	06-Feb-1997	Granted
<b>Title:</b> Electrical Connector Assembled From Wafers					
1056	IT	25969BE/03	25-Aug-2003	06-Feb-1997	Granted
<b>Title:</b> Electrical Connector Assembled From Wafers					
1056	KR	319306	18-Dec-2001	06-Feb-1997	Granted
<b>Title:</b> Electrical Connector Assembled From Wafers					
1056	US	5702258	30-Dec-1997	28-Mar-1996	Granted
<b>Title:</b> Electrical Connector Assembled From Wafers					
1056	US I	5860816	19-Jan-1999	24-Nov-1997	Granted
<b>Title:</b> Electrical Connector Assembled From Wafers					
1085	US	5885095	23-Mar-1999	28-May-1996	Granted
<b>Title:</b> Electrical Connector Assembly With Mounting Hardware And Protective Cover					
1091	DE	69814123D	02-May-2003	15-Jan-1998	Granted
<b>Title:</b> High Speed, High Density Electrical Connector					
1091	EP	1021854	02-May-2003	15-Jan-1998	Granted
<b>Title:</b> High Speed, High Density Electrical Connector					
1091	FR	1021854	02-May-2003	15-Jan-1998	Granted
<b>Title:</b> High Speed, High Density Electrical Connector					
1091	GB	1021854	02-May-2003	15-Jan-1998	Granted
<b>Title:</b> High Speed, High Density Electrical Connector					
1091	MX	212198	17-Dec-2002	15-Jan-1998	Granted
<b>Title:</b> High Speed, High Density Electrical Connector					
1091	US	5993259	30-Nov-1999	07-Feb-1997	Granted
<b>Title:</b> High Speed, High Density Electrical Connector					
1091	US	6238245	29-May-2001	26-Aug-1999	Granted
<b>Title:</b> High Speed, High Density Electrical Connector					

Case #	Country	Patent #	Issue Date	Filing Date	Status
1103	DE	69805426	15-May-2002	15-Jan-1998	Granted
					<b>Title:</b> HIGH SPEED, HIGH DENSITY ELECTRICAL CONNECTOR
1103	EP	1021855	15-May-2002	15-Jan-1998	Granted
					<b>Title:</b> HIGH SPEED, HIGH DENSITY ELECTRICAL CONNECTOR
1103	FR	1021855	15-May-2002	15-Jan-1998	Granted
					<b>Title:</b> HIGH SPEED, HIGH DENSITY ELECTRICAL CONNECTOR
1103	GB	1021855	15-May-2002	15-Jan-1998	Granted
					<b>Title:</b> HIGH SPEED, HIGH DENSITY ELECTRICAL CONNECTOR
1103	IE	1021855	15-May-2002	15-Jan-1998	Granted
					<b>Title:</b> HIGH SPEED, HIGH DENSITY ELECTRICAL CONNECTOR
1103	MX	212197	17-Dec-2002	15-Jan-1998	Granted
					<b>Title:</b> HIGH SPEED, HIGH DENSITY ELECTRICAL CONNECTOR
1103	NL	1021855	15-May-2002	15-Jan-1998	Granted
					<b>Title:</b> HIGH SPEED, HIGH DENSITY ELECTRICAL CONNECTOR
1103	SE	1021855	15-May-2002	15-Jan-1998	Granted
					<b>Title:</b> HIGH SPEED, HIGH DENSITY ELECTRICAL CONNECTOR
1103	US	5980321	09-Nov-1999	07-Feb-1997	Granted
					<b>Title:</b> HIGH SPEED, HIGH DENSITY ELECTRICAL CONNECTOR
1103	US	6299483	09-Oct-2001	26-Aug-1999	Granted
					<b>Title:</b> HIGH SPEED, HIGH DENSITY ELECTRICAL CONNECTOR
1151	CN	99813967.X	27-Apr-2005	01-Jun-2001	Granted
					<b>Title:</b> Printed Circuit Board and Method for Fabricating Such Board
1151	MX	223480	13-Oct-2004	01-Jun-2001	Granted
					<b>Title:</b> Printed Circuit Board and Method for Fabricating Such Board
1151	US	6181219	30-Jan-2001	02-Dec-1998	Granted
					<b>Title:</b> Printed Circuit Board and Method for Fabricating Such Board
1151	EP	1138180	24-Mar-2004	02-Dec-1999	Granted
					<b>Title:</b> Printed Circuit Board and Method for Fabricating Such Board
1151	FR	1138180	TBD	02-Dec-1999	Granted
					<b>Title:</b> Printed Circuit Board and Method for Fabricating Such Board
1151	NE	1138180	TBD	02-Dec-1999	Granted
					<b>Title:</b> Printed Circuit Board and Method for Fabricating Such Board
1151	DE	69915874.5	TBD	02-Dec-1999	Granted
					<b>Title:</b> Printed Circuit Board and Method for Fabricating Such Board
1154	CN	1127780	12-Nov-2003	24-May-2001	Granted
					<b>Title:</b> ELECTRICAL CONNECTOR
1154	EP	1133812	31-Mar-2004	22-Nov-1999	Granted
					<b>Title:</b> ELECTRICAL CONNECTOR
1154	DE	69916100	31-Mar-2004	22-Nov-1999	Granted
					<b>Title:</b> ELECTRICAL CONNECTOR
1154	FR	1133812	31-Mar-2004	22-Nov-1999	Granted
					<b>Title:</b> ELECTRICAL CONNECTOR
1154	GB	1133812	31-Mar-2004	22-Nov-1999	Granted
					<b>Title:</b> ELECTRICAL CONNECTOR
1154	US	6530790	11-Mar-2003	24-Nov-1998	Granted
					<b>Title:</b> ELECTRICAL CONNECTOR
1154	US	6537087	25-Mar-2003	25-Jan-2002	Granted
					<b>Title:</b> ELECTRICAL CONNECTOR

Case #	Country	Patent #	Issue Date	Filing Date	Status
1220	US	6379188	30-Apr-2002	24-Nov-1998	Granted
		<b>Title:</b> Differential Signal Electrical Connectors			
1220	US D1	6503103	07-Jan-2003	22-Jun-2000	Granted
		<b>Title:</b> Differential Signal Electrical Connectors			
1220	US D2	6554647	29-Apr-2003	22-Jun-2000	Granted
		<b>Title:</b> Differential Signal Electrical Connectors			
1220	US D3	6607402	19-Aug-2003	08-Apr-2002	Granted
		<b>Title:</b> Differential Signal Electrical Connectors			
1221	US	6565387	20-May-2003	30-Jun-1999	Granted
		<b>Title:</b> Modular Electrical Connector and Connector System			
1221	MX	228505	15-Jun-2005	19-Dec-2001	Granted
		<b>Title:</b> Modular Electrical Connector and Connector System			
1227	CN	1139151	-Feb-2004	22-Nov-1999	Granted
		<b>Title:</b> Electrical Connector with Impedance Balancing Sections			
1227	EP	1145386	24-Mar-2004	22-Nov-1999	Granted
		<b>Title:</b> Electrical Connector with Impedance Balancing Sections			
1227	US	6394822	28-May-2002	24-Nov-1998	Granted
		<b>Title:</b> Electrical Connector with Impedance Balancing Sections			
1228	US	6152747	28-Nov-2000	24-Nov-1998	Granted
		<b>Title:</b> Electrical Connector with End of Row Contacts to Equalize Performance			
1284	US	6388208	14-May-2002	23-Jul-1999	Granted
		<b>Title:</b> Multi-Connection VIA with Electrically Isolated Segments			
1285	US	6137064	24-Oct-2000	23-Jul-1999	Granted
		<b>Title:</b> SPLIT VIA SURFACE MOUNT CONNECTOR AND RELATED TECHNIQUES			
1302	US	6593535	15-Jul-2003	26-Jun-2001	Granted
		<b>Title:</b> DIRECT INNER LAYER INTERCONNECT FOR A HIGH SPEED PRINTED CIRCUIT BOARD			
1325	US	6293827	25-Sep-2001	03-Feb-2000	Granted
		<b>Title:</b> Differential Signal Electrical Connector			
1326	US	6517360	11-Feb-2003	11-Jun-2001	Granted
		<b>Title:</b> HIGH SPEED PRESSURE MOUNT CONNECTOR			
1327	DE	1256145	24-Nov-2004	30-Jan-2001	Granted
		<b>Title:</b> CONNECTOR WITH EGG-CRATE SHIELDING			
1327	EP	1256145	24-Nov-2004	30-Jan-2001	Granted
		<b>Title:</b> CONNECTOR WITH EGG-CRATE SHIELDING			
1327	FR	1256145	24-Nov-2004	30-Jan-2001	Granted
		<b>Title:</b> CONNECTOR WITH EGG-CRATE SHIELDING			
1327	TW	156867	26-Sep-2002	18-May-2001	Granted
		<b>Title:</b> CONNECTOR WITH EGG-CRATE SHIELDING			
1327	US	6506076	14-Jan-2003	31-Jan-2001	Granted
		<b>Title:</b> CONNECTOR WITH EGG-CRATE SHIELDING			

Case #	Country	Patent #	Issue Date	Filing Date	Status
1380	US	6639154	28-Oct-2003	10-Oct-2000	Granted
<b>Title:</b>	Methods and Apparatus For Forming A Connection between A Circuit Board And A Connector				
1383	US	6352436	05-Mar-2002	29-Jun-2000	Granted
<b>Title:</b>	Self-Retained Pressure Connection				
1388	US	6520686	18-Feb-2003	09-Nov-2000	Granted
<b>Title:</b>	Method and Apparatus for Forming a Fiber Optic Connection				
1388	US	6616342	09-Sep-2003	01-Oct-2002	Granted
<b>Title:</b>	Method and Apparatus for Forming a Fiber Optic Connection				
1393	US	6452379	17-Sep-2002	20-Oct-2000	Granted
<b>Title:</b>	Methods and Apparatus for Connecting to A Signal Launch				
1393	US 1	6717398	06-Apr-2004	22-Jul-2002	Granted
<b>Title:</b>	Methods and Apparatus for Connecting to A Signal Launch				
1394	US	6511229	28-Jan-2003	21-Dec-2000	Granted
<b>Title:</b>	Methods and Apparatus for Controlling Access to An Optical Interface				
1395	US	6516105	04-Feb-2003	10-Oct-2000	Granted
<b>Title:</b>	Optical Backplane Assembly and Method of Making Same				
1396	US	6619854	16-Sep-2003	31-Jan-2001	Granted
<b>Title:</b>	Techniques for Cleaning An Optical Interface of An Optical Connection System				
1405	US	6588943	08-Jul-2003	07-Aug-2000	Granted
<b>Title:</b>	Electro-Optic Connector Module				
1410	EP	1360533	23-Mar-2005	30-Jan-2002	Granted
<b>Title:</b>	Techniques for Selectively Exposing and Protecting An Optical Interface Using Film				
1410	DE	60203372	23-Mar-2005	30-Jan-2002	Granted
<b>Title:</b>	Techniques for Selectively Exposing and Protecting An Optical Interface Using Film				
1410	FR	1360533	23-Mar-2005	30-Jan-2002	Granted
<b>Title:</b>	Techniques for Selectively Exposing and Protecting An Optical Interface Using Film				
1410	GB	1360533	23-Mar-2005	30-Jan-2002	Granted
<b>Title:</b>	Techniques for Selectively Exposing and Protecting An Optical Interface Using Film				
1410	US	6547444	15-Apr-2003	31-Jan-2001	Granted
<b>Title:</b>	Techniques for Selectively Exposing and Protecting An Optical Interface Using Film				
1437	TW	205664	26-Oct-2004	15-Jan-2002	Granted
<b>Title:</b>	Connector Molding Method and Shielded Waferized Connector Made Therefrom				
1437	US	6409543	25-Jun-2002	25-Jan-2001	Granted
<b>Title:</b>	Connector Molding Method and Shielded Waferized Connector Made Therefrom				
1437	US	6602095	05-Aug-2003	24-Apr-2002	Granted
<b>Title:</b>	Connector Molding Method and Shielded Waferized Connector Made Therefrom				
1447	US	5945838	31-Aug-1999	26-Jun-1997	Granted
<b>Title:</b>	Apparatus for Testing Circuit Boards				
1448	US	6334784	01-Jan-2002	07-Aug-2000	Granted
<b>Title:</b>	Z-Axis Pressure Mount Connector Fixture				

Case #	Country	Patent #	Issue Date	Filing Date	Status
1477	US	6736546	18-May-2004	16-Jul-2002	Granted
<b>Title:</b> Optical Connector Ferrule Designed to Minimize Manufacturing Imperfections and Mating Misalignments by Incorporating Exact Constraint Principles					
1481	US	6641410	04-Nov-2003	07-Jun-2001	Granted
<b>Title:</b> Electrical Solder Ball Contact					
1482	US	6592381	15-Jul-2003	25-Jan-2001	Granted
<b>Title:</b> Waferized Power Connector					
1485	EP	1358697	04-May-2005	01-Feb-2002	Granted
<b>Title:</b> Matrix Connector					
1485	US	6769935	03-Aug-2004	01-Feb-2002	Granted
<b>Title:</b> Matrix Connector					
1486	US	6547445	15-Apr-2003	06-Feb-2001	Granted
<b>Title:</b> High-Density Fiber Optic Backplane					
1489	US	6541712	01-Apr-2003	04-Dec-2001	Granted
<b>Title:</b> High Speed Multi-Layer Printed Circuit Board VIA					
1524	US	6769814	03-Aug-2004	16-Jul-2002	Granted
<b>Title:</b> Waferized Fiber Optic Connector					
1615	US	6739918	25-May-2004	01-Feb-2002	Granted
<b>Title:</b> SELF-ALIGNING ELECTRICAL CONNECTOR					
1617	US	6839935	11-Jan-2005	29-May-2002	Granted
<b>Title:</b> Methods and Apparatus for Cleaning Optical Connectors					
1636	US	6764349	20-Jul-2004	29-Mar-2002	Granted
<b>Title:</b> Matrix Connector with Integrated Power Contacts					
1684	US	6709294	23-Mar-2004	17-Dec-2002	Granted
<b>Title:</b> Electrical Connector with Conductive Plastic Features					
1718	US	6832858	21-Dec-2004	13-Sep-2002	Granted
<b>Title:</b> Techniques for Forming Fiber Optic Connectors In A Modularized Manner					

Case #	Country	Patent #	Issue Date	Filing Date	Status
1719	US	6762941	13-Jul-2004	15-Jul-2002	Granted
<b>Title:</b> Techniques for Connecting A Set of Connecting Elements Using An Improved Latching Apparatus					
1734	DE	3751977.8	10-Sep-1987		Granted
<b>Title:</b> Reinforced Plastic Laminates for Use in the Production of Printed Circuit Boards and Process for Making Such Laminates and Resulting Products					
1734	FR	0326577	10-Sep-1987		Granted
<b>Title:</b> Reinforced Plastic Laminates for Use in the Production of Printed Circuit Boards and Process for Making Such Laminates and Resulting Products					
1734	GB	0326577	10-Sep-1987		Granted
<b>Title:</b> Reinforced Plastic Laminates for Use in the Production of Printed Circuit Boards and Process for Making Such Laminates and Resulting Products					
1734	US	5037691	06-Aug-1991	23-Aug-1989	Granted
<b>Title:</b> Reinforced Plastic Laminates for Use in the Production of Printed Circuit Boards and Process for Making Such Laminates and Resulting Products					
1735	JP	2129158	10-Sep-1997	10-Sep-1987	Granted
<b>Title:</b> Printed Circuit Board Made of Reinforced Synthetic Resin Laminates					
1736	JP	2138554	04-Oct-1995	10-Sep-1987	Granted
<b>Title:</b> Method for Making Reinforced Plastic Laminates for Use in Production of Circuit Boards					
1736	JP	2637378	25-Apr-1997	10-Sep-1987	Granted
<b>Title:</b> Method for Making Reinforced Plastic Laminates for Use in Production of Circuit Boards					
1736	US	4943334	24-Jul-1990	15-Sep-1986	Granted
<b>Title:</b> Method for Making Reinforced Plastic Laminates for Use in Production of Circuit Boards					
1740	US	5478421	26-Dec-1995	28-Sep-1993	Granted
<b>Title:</b> Method for Making Composite Structures by Filament Winding					
1757	US	6786771	07-Sep-2004	20-Dec-2002	Granted
<b>Title:</b> Interconnection System With Improved High Frequency Performance					
1766	US	6776645	17-Aug-2004	20-Dec-2002	Granted
<b>Title:</b> LATCH AND RELEASE SYSTEM FOR A CONNECTOR					
1778	US	6776659	17-Aug-2004	26-Jun-2003	Granted
<b>Title:</b> High Speed, High Density Electrical Connector					
1806	US	6827611	07-Dec-2004	18-Jun-2003	Granted
<b>Title:</b> Electrical Connector with Multi-Beam Contact					



<b>Case #</b>	<b>Country</b>	<b>Patent #</b>	<b>Issue Date</b>	<b>Filing Date</b>	<b>Status</b>
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1824	US	6814619	09-Nov-2004	26-Jun-2003	Granted
<b>Title:</b> High Speed, High Density Electrical Connector And Connector Assembly					

1825	US	6780059	24-Aug-2004	26-Jun-2003	Granted
<b>Title:</b> High Speed, High Density Electrical Connector					

1849	US	6872085	29-Mar-2005	29-Sep-2003	Granted
<b>Title:</b> HIGH SPEED, HIGH DENSITY ELECTRICAL CONNECTOR ASSEMBLY					

**Patent Applications:**

Case #	Country		Filing Date	Status	
05-2021	US		60/691,423 17-Jun-2005	Pending	
<b>Title:</b> A COMPUTER SYSTEM FOR MODELING LOSS ACROSS A BACKPLANE AND AN ASSOCIATED METHOD OF USE					
1011	JP	521651/96	04-Dec-1995	Published	
<b>Title:</b> CIRCUIT BOARD CONNECTORS <span style="float: right;">PRINTED</span>					
1056	JP	97/534383	06-Feb-1997	Published	
<b>Title:</b> Electrical Connector Assembled From Wafers					
1091	CA	2280173	05-Aug-1999	Pending	
<b>Title:</b> Speed, High Density Electrical Connector <span style="float: right;">High</span>					
1091	JP	534683/98	09-Aug-1999	Published	
<b>Title:</b> Speed, High Density Electrical Connector <span style="float: right;">High</span>					
1091	KR	1999-7007149		06-Aug-1999	Granted (Pat # 517158)
<b>Title:</b> Speed, High Density Electrical Connector <span style="float: right;">High</span>					
1103	CA	2280174	15-Jan-1998	Pending	
<b>Title:</b> SPEED, HIGH DENSITY ELECTRICAL CONNECTOR <span style="float: right;">HIGH</span>					
1103	JP	534510/98	09-Aug-1999	Published	
<b>Title:</b> SPEED, HIGH DENSITY ELECTRICAL CONNECTOR <span style="float: right;">HIGH</span>					
1103	KR	1999-7007150		06-Aug-1999	Published
<b>Title:</b> SPEED, HIGH DENSITY ELECTRICAL CONNECTOR <span style="float: right;">HIGH</span>					
1151	CA	2352820	30-May-2001	Pending	
<b>Title:</b> Circuit Board and Method for Fabricating Such Board <span style="float: right;">Printed</span>					
1151	EP	99962969.4	02-Dec-1999	Granted	(Pat # 1138180)
<b>Title:</b> <span style="float: right;">Printed</span>					

Circuit Board and Method for Fabricating Such Board			
1151	JP	2000-586144	04-Jun-2001 Published
<b>Title:</b>			Printed
Circuit Board and Method for Fabricating Such Board			

1154	EP	04000082.0	06-Jan-2004 Published
<b>Title:</b>			
ELECTRICAL CONNECTOR			
1154	JP	2000-584560	24-May-2001 Published
<b>Title:</b>			
ELECTRICAL CONNECTOR			

Case #	Country		Filing Date	Status
1220	CA	2392322	22-May-2002	Pending
<b>Title:</b>				Differential Signal Electrical Connectors
1220	CA	2461037	24-Nov-1999	Pending
<b>Title:</b>				Differential Signal Electrical Connectors
1220	CN	99817015.1	23-May-2002	Published
<b>Title:</b>				Differential Signal Electrical Connectors
1220	CN	0410033454.5	08-Apr-2004	Published
<b>Title:</b>				Differential Signal Electrical Connectors
1220	EP	99962856.3	24-Nov-1999	Published
<b>Title:</b>				Differential Signal Electrical Connectors
1220	EP	04002034.9	24-Nov-1999	Published
<b>Title:</b>				Differential Signal Electrical Connectors
1220	EP	04028406.9	01-Dec-2004	Published
<b>Title:</b>				Differential Signal Electrical Connectors
1220	JP	2001-540892	23-May-2002	Published
<b>Title:</b>				Differential Signal Electrical Connectors
1220	JP	2004-56190	01-Mar-2004	Pending
<b>Title:</b>				Differential Signal Electrical Connectors
1220	KR	2002-7006695	24-May-2002	Published
<b>Title:</b>				Differential Signal Electrical Connectors
1220	KR	2004-7008353	31-May-2004	Pending
<b>Title:</b>				Differential Signal Electrical Connectors

1220	MX	2002/005163	24-Nov-1999	Pending	
<b>Title:</b>					Differential Signal Electrical Connectors
1220	MX	2004/003001	24-Nov-1999	Pending	
<b>Title:</b>					Differential Signal Electrical Connectors

1221	CA	2377396	21-Jun-2000	Pending	
<b>Title:</b>					Modular Electrical Connector and Connector System
1221	EP	00943009.1	21-Jun-2000	Published (Will grant on 11/30/05)	
<b>Title:</b>					Modular Electrical Connector and Connector System

1227	JP	2000-584561	24-May-2001	Published	
<b>Title:</b>					Electrical Connector with Impedance Balancing Sections

1325	JP	2001-557119	05-Aug-2002	Pending	
<b>Title:</b>					Differential Signal Electrical Connector

1326	EP	03029590.1	23-Dec-2003	Published	
<b>Title:</b>					HIGH SPEED PRESSURE MOUNT CONNECTOR
1326	JP	2001-557118	05-Aug-2002	Pending	
<b>Title:</b>					HIGH SPEED PRESSURE MOUNT CONNECTOR

Case #	Country		Filing Date	Status	
1327	CA	2399960	31-Jul-2002	Pending	
<b>Title:</b>					CONNECTOR WITH EGG-CRATE SHIELDING
1327	CN	01804535.9	05-Aug-2002	Published	
<b>Title:</b>					CONNECTOR WITH EGG-CRATE SHIELDING
1327	IL	151055	01-Aug-2002	Pending	
<b>Title:</b>					CONNECTOR WITH EGG-CRATE SHIELDING

1327	JP	2001-557116	05-Aug-2002	Pending	
<b>Title:</b>		CONNECTOR WITH EGG-CRATE SHIELDING			
1327	KR	2002-7010001	02-Aug-2002	Published	
<b>Title:</b>		CONNECTOR WITH EGG-CRATE SHIELDING			
1327	MX	2002/007546	05-Aug-2002	Pending	
<b>Title:</b>		CONNECTOR WITH EGG-CRATE SHIELDING			

1394	CA	2431346	16-Jun-2003	Pending	
<b>Title:</b>		and Apparatus for Controlling Access to An Optical Interface			
1394	CN	01821104.6	19-Dec-2001	Published	Methods
<b>Title:</b>		and Apparatus for Controlling Access to An Optical Interface			
1394	EP	00991358.1	19-Dec-2001	Pending	Methods
<b>Title:</b>		and Apparatus for Controlling Access to An Optical Interface			
1394	JP	2002-551629	17-Jun-2003	Published	Methods
<b>Title:</b>		and Apparatus for Controlling Access to An Optical Interface			
1394	MX	2003/005541	19-Dec-2001	Published	Methods
<b>Title:</b>		and Apparatus for Controlling Access to An Optical Interface			

1405	CN	01813871.3	08-Feb-2003	Published	
<b>Title:</b>		Electro-Optic Connector Module			
1405	EP	01952858.7	20-Jul-2001	Published	
<b>Title:</b>		Electro-Optic Connector Module			
1405	JP	2002-517268	07-Feb-2003	Published	
<b>Title:</b>		Electro-Optic Connector Module			

1410	JP	2002-561992	30-Jan-2002	Published	
<b>Title:</b>		Techniques for Selectively Exposing and Protecting An Optical Interface Using Film			
1410	MX	2003/006844	31-Jul-2003	Published	
<b>Title:</b>		Techniques for Selectively Exposing and Protecting An Optical Interface Using Film			

1437	CA	2435759	23-Jan-2002	Pending	
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**Title:**  
Connector Molding Method and Shielded Waferized Connector Made Therefrom  
1437 CN 02804171.2 25-Jan-2002 Published

**Title:**  
Connector Molding Method and Shielded Waferized Connector Made Therefrom  
1437 EP 02720835.4 23-Jan-2002 Published

**Title:**  
Connector Molding Method and Shielded Waferized Connector Made Therefrom  
1437 JP 2002-560236 23-Jan-2002 Published

**Title:**  
Connector Molding Method and Shielded Waferized Connector Made Therefrom  
1437 MX 2003/006690 25-Jul-2003 Published

**Title:**  
Connector Molding Method and Shielded Waferized Connector Made Therefrom

Case #	Country	Filing Date	Status
1477	CA	2469301	29-Aug-2002 Pending
<b>Title:</b>			Optical
Connector Ferrule Designed to Minimize Manufacturing Imperfections and Mating Misalignments by Incorporating Exact Constraint Principles			
1477	CN	02821606.7	29-Aug-2002 Pending
<b>Title:</b>			Optical
Connector Ferrule Designed to Minimize Manufacturing Imperfections and Mating Misalignments by Incorporating Exact Constraint Principles			
1477	EP	02766158.6	29-Aug-2002 Published
<b>Title:</b>			Optical
Connector Ferrule Designed to Minimize Manufacturing Imperfections and Mating Misalignments by Incorporating Exact Constraint Principles			
1477	JP	2003-525350	01-Mar-2004 Pending
<b>Title:</b>			Optical
Connector Ferrule Designed to Minimize Manufacturing Imperfections and Mating Misalignments by Incorporating Exact Constraint Principles			

1482	CN	02804169.0	23-Jan-2002 Pending
<b>Title:</b>			
Waferized Power Connector			
1482	EP	02705906.2	23-Jan-2002 Pending
<b>Title:</b>			
Waferized Power Connector			
1482	JP	2002-560238	23-Jan-2002 Published
<b>Title:</b>			
Waferized Power Connector			
1482	MX	2003/006691	25-Jul-2003 Published
<b>Title:</b>			
Waferized Power Connector			

1485	CN	02805724.4	01-Feb-2002 Published
<b>Title:</b>			Matrix
Connector			

1485	JP	2002-561325	01-Feb-2002	Published	
<b>Title:</b>					Matrix
Connector					
1485	MX	2003/006895	01-Feb-2002	Pending	
<b>Title:</b>					Matrix
Connector					

1486	CN	02804622.6	05-Feb-2002	Pending	
<b>Title:</b>					High-
Density Fiber Optic Backplane					
1486	EP	02702147.6	05-Feb-2002	Pending	
<b>Title:</b>					High-
Density Fiber Optic Backplane					
1486	JP	2002-563051	05-Feb-2002	Published	
<b>Title:</b>					High-
Density Fiber Optic Backplane					

1489	TW	91135020	03-Dec-2002	Published	
<b>Title:</b>					High
Speed Multi-Layer Printed Circuit Board VIA					

1524	CA	2455903	29-Aug-2002	Pending	
<b>Title:</b>					
Waferized Fiber Optic Connector					
1524	CN	02816889.5	27-Feb-2004	Published	
<b>Title:</b>					
Waferized Fiber Optic Connector					
1524	EP	02768756.5	29-Aug-2002	Published	
<b>Title:</b>					
Waferized Fiber Optic Connector					

Case #	Country	Filing Date	Status
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1524	JP	2003-525351	27-Feb-2004	Published	
<b>Title:</b>					
Waferized Fiber Optic Connector					
1524	KR	2004-7002967	27-Feb-2004	Pending	
<b>Title:</b>					
Waferized Fiber Optic Connector					

1618	EP	03814958-9	24-Dec-2003	Published	
<b>Title:</b>					
System and Method for Inspecting an Optical Interface					
1618	US	10/329881	26-Dec-2002	Published	
<b>Title:</b>					
System and Method for Inspecting an Optical Interface					

1636	CN	03800362.7	01-Dec-2003	Published	
<b>Title:</b>					Matrix
Connector with Integrated Power Contacts					
1636	EP	03716816.8	25-Mar-2003	Published	
<b>Title:</b>					Matrix
Connector with Integrated Power Contacts					
1636	JP	2003-582862	29-Sep-2004	Pending	
<b>Title:</b>					Matrix
Connector with Integrated Power Contacts					

1684	EP	03814022.4	17-Dec-2003	Published	
<b>Title:</b>					
Electrical Connector with Conductive Plastic Features					

1693	EP	03814856.5	18-Dec-2003	Published	
<b>Title:</b>					Systems and Methods for Inspection An Optical Interface
1693	US	10/329881	26-Dec-2002	Pending	
<b>Title:</b>					Systems and Methods for Inspection An Optical Interface

1719	CN	03821632.9	11-Mar-2005	Published	
<b>Title:</b>					Techniques for Connecting A Set of Connecting Elements Using An Improved Latching Apparatus
1719	EP	03764595.9	15-Jul-2003	Published	
<b>Title:</b>					Techniques for Connecting A Set of Connecting Elements Using An Improved Latching Apparatus
1719	JP	2004-521766	11-Mar-2005	Pending	
<b>Title:</b>					Techniques for Connecting A Set of Connecting Elements Using An Improved Latching Apparatus

1721	CA	2459290	29-Aug-2002	Pending	
<b>Title:</b>					Modular
Fiber Optic Connection System					



Case #	Country		Filing Date	Status	
1721	CN	02819348.2	31-Mar-2004	Published	
		<b>Title:</b>			Modular
		Fiber Optic Connection System			
1721	EP	02797779.2	29-Aug-2002	Published	
		<b>Title:</b>			Modular
		Fiber Optic Connection System			
1721	JP	2003-525349	01-Mar-2004	Pending	
		<b>Title:</b>			Modular
		Fiber Optic Connection System			
1721	US	10/195960	16-Jul-2002	Published	
		<b>Title:</b>			Modular
		Fiber Optic Connection System			
1742	EP	03800022.0	20-Dec-2003	Pending	
		<b>Title:</b>	FERRULE ASSEMBLY AND METHODS THEREFOR		
1742	US	10/324816	20-Dec-2002	Published	
		<b>Title:</b>	FERRULE ASSEMBLY AND METHODS THEREFOR		
1757	EP	03814231.1	20-Dec-2003	Pending	
		<b>Title:</b>			
		Interconnection System With Improved High Frequency Performance			
1769	US	10/952103	28-Sep-2004	Pending	
		<b>Title:</b>			Star Routed Backplane
1769	WO	US05/34494	26-Sep-2005	Pending	
		<b>Title:</b>	Star Routed Backplane		
1772	EP	03783463.7	13-Nov-2003	Published	
		<b>Title:</b>	CONNECTOR AND PRINTED CIRCUIT BOARD FOR REDUCING CROSS-TALK		
1774	US	10/422515	24-Apr-2003	Pending	
		<b>Title:</b>			Printed
		Circuit Board Minimizing Undesirable Signal Reflections in a Via and Methods Therefor			
1774	WO	US04/012704	23-Apr-2004	Published	
		<b>Title:</b>			Printed
		Circuit Board Minimizing Undesirable Signal Reflections in a Via and Methods Therefor			
1783	US	10/954865	30-Sep-2004	Pending	
		<b>Title:</b>			Perpendicular Switch Card Architecture
1783	WO	US05/34595	28-Sep-2005	Pending	
		<b>Title:</b>	Perpendicular Switch Card Architecture		

1788	US	10/672779	26-Sep-2003	Published	
<b>Title:</b>	Protective Covers for Fiber Optic Connector				

1811	US	10/675647	03-Sep-2003	Published	
<b>Title:</b>					High
Speed, High Density Electrical Connector					
1811	WO	US04/028956	03-Sep-2004	Published	
<b>Title:</b>					High
Speed, High Density Electrical Connector					

Case #	Country		Filing Date	Status	
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1815	US	60/675217	27-Apr-2005	Pending	
<b>Title:</b>	Discharging Energy During Hot Plugging for Power Using Conductive Plastic				

1819	US	60/639064	23-Dec-2004	Pending	
<b>Title:</b>					BARE DIE SOCKET
1819	US	11/053448	08-Feb-2005	Pending	
<b>Title:</b>					BARE DIE SOCKET

1821	US	60/639041	23-Dec-2004	Pending	
<b>Title:</b>	ENVIRONMENTALLY SEALED CHIP SOCKET				
1821	US	11/059492	08-Feb-2005	Pending	
<b>Title:</b>	ENVIRONMENTALLY SEALED CHIP SOCKET				

1824	WO	US04/020170	23-Jun-2004	Published	
<b>Title:</b>	High Speed, High Density Electrical Connector And Connector Assembly				
1825	WO	US04/020109	23-Jun-2004	Published	
<b>Title:</b>	High Speed, High Density Electrical Connector				

1826	US	10/603048	24-Jun-2003	Published	
<b>Title:</b>					Printed
Circuit Board For High Speed, High Density Electrical Connector With Improved Cross-Talk Minimization, Attenuation And Impedance Mismatch Characteristics					
1826	WO	US04/19846	23-Jun-2004	Published	
<b>Title:</b>					Printed
Circuit Board For High Speed, High Density Electrical Connector With Improved Cross-Talk Minimization, Attenuation And Impedance Mismatch Characteristics					

1840	US	10/744328	23-Dec-2003	Pending	
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**Title:** HIGH  
 SPEED CONNECTOR ASSEMBLY  
 1840 WO US04/039063 19-Nov-2004 Pending  
**Title:** HIGH SPEED CONNECTOR ASSEMBLY

1855 US 10/741542 23-Dec-2003 Pending  
**Title:** Modular Rackmount Chiller  
 1855 WO US04/041964 13-Dec-2004 Pending  
**Title:** Modular Rackmount Chiller

1856 US 10/774050 23-Dec-2003 Pending  
**Title:** Modular Fiber Optic Connection System

1857 US 10/745475 23-Dec-2003 Pending  
**Title:** Fiber Optic Adapter Designed To Accommodate Different Style Ferrules

Case #	Country	Filing Date	Status
1874	US	10/886449	07-Jul-2004 Pending
<b>Title:</b> Atmospheric 2-Phase Electronics Cooling System			

1882	US	11/115874	27-Apr-2005 Pending
<b>Title:</b> Layer count reduction in backplane PCB			

1886	US	10/882598	01-Jul-2004 Pending
<b>Title:</b> Orthogonal optical edge connector			
1886	WO	US05/22487	24-Jun-2005 Pending
<b>Title:</b> Orthogonal optical edge connector			

1891	US	10/874837	23-Jun-2004 Pending
<b>Title:</b> Electrical Connector Incorporating Passive Circuit Elements			
1891	WO	US05/22423	23-Jun-2005 Pending
<b>Title:</b> Electrical Connector Incorporating Passive Circuit Elements			

1892	US	10/874669	23-Jun-2004 Pending
<b>Title:</b> Methods			
of Manufacturing An Electrical Connector Incorporating Passive Circuit			

Elements

1898	US	10/959652	06-Oct-2004	Pending
<b>Title:</b> GbX 1.85mm x 1.85 mid-plane x-connect				
1898	WO	US05/	06-Oct-2005	Pending
<b>Title:</b> GbX 1.85mm x 1.85 mid-plane x-connect				

1902	US	10/881248	30-Jun-2004	Pending
<b>Title:</b> Connector System for Optical Wave Guides				
1902	WO	TBD	24-Jun-2005	Pending
<b>Title:</b> Connector System for Optical Wave Guides				

1903	US	10/897638	23-Jul-2004	Pending
<b>Title:</b> Microwave Quality Reflect Standard To Improve In-Fixture Calibration				
1903	WO	US05/026075	22-Jul-2005	Pending
<b>Title:</b> Microwave Quality Reflect Standard To Improve In-Fixture Calibration				

1913	US	60/638973	24-Dec-2004	Pending
<b>Title:</b> MIDPLANE ESPECIALLY APPLICABLE TO AN ORTHOGONAL ARCHITECTURE ELECTRONIC SYSTEM				
1913	US	11/173927	01-Jul-2005	Pending
<b>Title:</b> MIDPLANE ESPECIALLY APPLICABLE TO AN ORTHOGONAL ARCHITECTURE ELECTRONIC SYSTEM				

Case #	Country		Filing Date	Status
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1915	US	10/954441	30-Sep-2004	Pending
<b>Title:</b> Modular Cooling Shelf				
1915	WO	US05/34596	28-Sep-2005	Pending
<b>Title:</b> Modular Cooling Shelf				

1918	US	10/955571	30-Sep-2004	Pending
<b>Title:</b> High Speed, High Density Electrical Connector				
1918	WO	US05/34605	28-Sep-2005	Pending
<b>Title:</b> High Speed, High Density Electrical Connector				

1943	US	60/638971	24-Dec-2004	Pending
<b>Title:</b>				

DIFFERENTIAL ELECTRICAL CONNECTOR ASSEMBLY  
1943 US 11/173926 01-Jul-2005 Pending  
**Title:**  
DIFFERENTIAL ELECTRICAL CONNECTOR ASSEMBLY

1952 US 11/011838 14-Dec-2004 Pending  
**Title:** Front-To-Back Air Cooling Architecture For Orthogonal Board Architectures

1973 US 11/220382 06-Sep-2005 Pending  
**Title:** Bi-Directional Electrical Path for Contact End

05-2019 US 60/695705 30-Jun-2005 Pending  
**Title:** TRIPOLI  
05-2019 US 11/183564 18-Jul-2005 Pending  
**Title:** TRIPOLI

05-2028 US 60/695264 30-Jun-2005 Pending  
**Title:** CONDUCTIVE INSERTS

05-2029 US 60/695308 30-Jun-2005 Pending  
**Title:** CONNECTOR WITH OFFSET DIFFERENTIAL SIGNAL CONDUCTORS

**Patent Disclosures:**

Case No	Status	Title
05-2036	Open	EXTRACTION OF PHYSICALLY CONSISTENT, FREQUENCY-DEPENDENT DIELECTRIC PROPERTIES OF PCB TRANSMISSION LINES
05-2037	Open	LOSSY MATERIAL DISPOSED BETWEEN DIFFERENTIAL PAIRS OF SIGNAL CONDUCTORS IN AN INTERCONNECTION DEVICE
05-2040	Open	THICK FILM RESISTORS AND OTHER COMPONENTS INTEGRATED INTO A CONNECTOR
1919	Open	MATCHED IMPEDANCE PLATED THROUGH HOLE FOR THE INTERCONNECTION OF TWO CONNECTORS
1976	Open	STIFFENER-ORGANIZER FOR CONNECTOR TO IMPROVE WAFER POSITIONING & ATTACHMENT REFLOW
05-2002	Authorized	SMT PIN WITH NOTCH/DIMPLE FOR SOLDERING AND ADHESIVE ATTACHMENT [Note: Awaiting Inventor signatures - will be filed as US provisional application on November 30, 2005 if inventors have not responded]
05-2003	Authorized	FOLDED-DISK PIN FOR SMT SOLDER AND/OR COMPOUND ATTACHMENT [Note: Awaiting Inventor signatures - will be filed as US provisional application on November 30, 2005 if inventors have not responded]

**Patent Disclosures:**

<b>Case No</b>	<b>Status</b>	<b>Title</b>
05-2036	Open	EXTRACTION OF PHYSICALLY CONSISTENT, FREQUENCY-DEPENDENT DIELECTRIC PROPERTIES OF PCB TRANSMISSION LINES
05-2037	Open	LOSSY MATERIAL DISPOSED BETWEEN DIFFERENTIAL PAIRS OF SIGNAL CONDUCTORS IN AN INTERCONNECTION DEVICE
05-2040	Open	THICK FILM RESISTORS AND OTHER COMPONENTS INTEGRATED INTO A CONNECTOR
1919	Open	MATCHED IMPEDANCE PLATED THROUGH HOLE FOR THE INTERCONNECTION OF TWO CONNECTORS.
1976	Open	STIFFENER-ORGANIZER FOR CONNECTOR TO IMPROVE WAFER POSITIONING & ATTACHMENT REFLOW
05-2002	Authorized	SMT PIN WITH NOTCH/DIMPLE FOR SOLDERING AND ADHESIVE ATTACHMENT
05-2003	Authorized	FOLDED-DISK PIN FOR SMT SOLDER AND/OR COMPOUND ATTACHMENT

**Trademarks:**

Mark	Class	Serial No.	Filing Date	Registration Number.	Registration Date	Status
CROSSBOW	IC 009	78682550	August 1, 2005	N/A	N/A	Pending
VENTURA	IC 009	78418881	May 14, 2004	N/A	N/A	Pending
APTERA	IC 009	78514820	November 10, 2004	N/A	N/A	Pending
DIFFERENTIAL CLEARANCE TECHNOLOGY	IC 009	78297381	September 8, 2003	N/A	N/A	Pending
NEXLEV	IC 009	78107484	February 7, 2002	2669292	December 31, 2002	Registered
GBX	IC 009	76474185	December 12, 2002	2779372	November 4, 2003	Registered
BRINGING BANDWIDTH TO THE GLOBAL NETWORK	IC 009	75862605	December 2, 1999	2426683	February 6, 2001	Registered
VHDM	IC 009	75383873	November 3, 1997	2423664	January 23, 2001	Registered
HDM PLUS	IC 009	74350016	January 21, 1993	1894556	May 16, 1995	Registered
HDM	IC 009	74353156	January 21, 1993	1886552	March 28, 1995	Registered
HIGH DENSITY PLUS (HD+)	IC 009	73688734	October 9, 1987	1494014	June 28, 1988	Registered

**Service Marks:**

Mark	Class	Serial No.	Filing Date	Registration Number	Registration Date	Status
DESIGNLINK	IC 042	78470448	August 19, 2004	N/A	N/A	Pending



## SCHEDULE B

### Intellectual Property Licensed from Buyer to Assignor

#### Granted Patents Re: DCT Technology

Case #	Country	Patent #	Issue Date	Filing Date	Status
1220	US D3	6607402	19-Aug-2003	08-Apr-2002	Granted
Title: Differential Signal Electrical Connectors					

#### Patent Applications Re: DCT Technology

Case #	Country	Patent #	Issue Date	Filing Date	Status
1220	CA	2392322		22-May-2002	Pending
Title: Differential Signal Electrical Connectors					
1220	CN	0410033454.5		08-Apr-2004	Published
Title: Differential Signal Electrical Connectors					
1220	EP	04028406.9		01-Dec-2004	Published
Title: Differential Signal Electrical Connectors					
1220	JP	2004-56190		01-Mar-2004	Pending
Title: Differential Signal Electrical Connectors					
1220	KR	2004-7008353		31-May-2004	Pending
Title: Differential Signal Electrical Connectors					
1220	MX	2004/003001		24-Nov-1999	Pending
Title: Differential Signal Electrical Connectors					

#### Patent Applications Re: DESIGNLINK

Case #	Country	Patent #	Issue Date	Filing Date	Status
05-2021	US	60/691423		17-Jun-2005	Pending
Title: A COMPUTER SYSTEM FOR MODELING LOSS ACROSS A BACKPLANE AND AN ASSOCIATED METHOD OF USE					

**SCHEDULE C**

**Trademarks Licensed from Assignor to Buyer Subject to Certain Conditions**

TCS